# Advance Information

# Low Dropout Linear Regulators with Watchdog, RESET, and Wake Up

The NCV8508 is a precision micropower voltage regulator family. The part contains many of the required operational requirements for powering microprocessors. Its' robustness makes it suitable for severe automotive environments. The devices low dropout voltage ensures operation of loads (i.e. microprocessors) when the battery voltage is low such as during the cranking cycle of an automobile. In addition to being a good fit for the automotive environment, the NCV8508 is ideal for use in battery operated, microprocessor controlled equipment because of it's extremely low quiescent current.

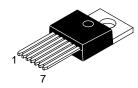
#### **Features**

- Output Voltage Options: 3.3 V or 5.0 V
- ± 2.0% Output Voltage
- IOUT Up to 250 mA
- Micropower Compatible Control Functions:
  - Wake Up
  - Watchdog
  - RESET
- Low Dropout Voltage:
  - 250 mV @ 150 mV
- Low Quiescent Current (100 µA typ)
- Protection Features:
  - Thermal Shutdown
  - Short Circuit
  - 45 V Operation
- Internally Fused Leads in SO-16L Package

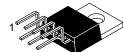


#### ON Semiconductor™

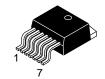
http://onsemi.com



TO-220 SEVEN LEAD T SUFFIX CASE 821E



TO-220 SEVEN LEAD TV SUFFIX CASE 821J



D<sup>2</sup>PAK 7-PIN D2T SUFFIX CASE 936H



SO-8 D SUFFIX CASE 751



SO-16L DW SUFFIX CASE 751G

#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 9 of this data sheet.

#### **DEVICE MARKING INFORMATION**

See general marking information in the device marking section on page 9 of this data sheet.

#### **PIN CONNECTIONS**

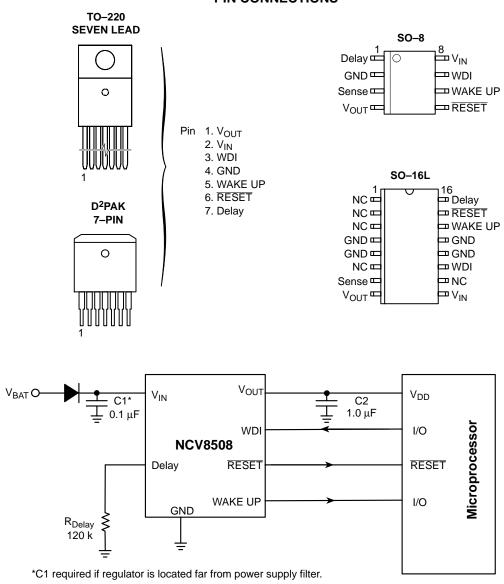


Figure 1. Application Circuit

#### **MAXIMUM RATINGS\***

Rating			Unit
Input Voltage, V <sub>IN</sub>		-0.3 to 45	V
Output Voltage, V <sub>OUT</sub>		-0.3 to 18	V
ESD Susceptibility (Human Body Model)		2.0	kV
Logic Inputs/Outputs (Reset, WDI, Wakeup)		-0.3 to +7.0	V
Operating Junction Temperature, T <sub>J</sub>		-40 to150	°C
Storage Temperature Range, T <sub>S</sub>		-55 to +150	°C
Lead Temperature Soldering: Wa	ve Solder (through hole styles only) (Note 1.) Reflow: (SMD styles only) (Note 2.)	260 peak 230 peak	°C

<sup>1. 10</sup> second maximum.

<sup>2. 60</sup> second maximum above 183°C.

<sup>\*</sup>The maximum package power dissipation must be observed.

**ELECTRICAL CHARACTERISTICS** ( $-40^{\circ}C \le T_{J} \le 125^{\circ}C$ ; 6.0 V  $\le$  V<sub>IN</sub>  $\le 28$  V, 100  $\mu$ A  $\le$  I<sub>OUT</sub>  $\le 150$  mA, C<sub>2</sub> = 1.0  $\mu$ F, R<sub>Delay</sub> = 120 k; unless otherwise specified.)

Characteristic	Test Conditions	Min	Тур	Max	Unit
Output Selection					
Output Voltage, V <sub>OUT</sub> for 3.3 V Option	-	3.234	3.300	3.366	V
Output Voltage, V <sub>OUT</sub> for 5.0 V Option	-	4.90	5.00	5.10	V
Dropout Voltage (V <sub>IN</sub> – V <sub>OUT</sub> )	I <sub>OUT</sub> = 150 mA. Note 3.	-	250	500	mV
Load Regulation	V <sub>IN</sub> = 14 V, 5.0 mA < I <sub>OUT</sub> < 150 mA	-	5.0	30	mV
Line Regulation	I <sub>OUT</sub> = 5.0 mA	-	5.0	20	mV
Current Limit	-	250	400	-	mA
Thermal Shutdown	Guaranteed by Design	150	180	210	°C
Quiescent Current	V <sub>IN</sub> = 12 V, I <sub>OUT</sub> = 250 mA	-	100	150	μΑ
RESET					
Threshold for 3.3 V Option	-	2.970	3.069	3.168	٧
Threshold for 5.0 V Option	reshold for 5.0 V Option –		4.65	4.80	V
Output Low	$R_{LOAD} = 10 \text{ k to } V_{OUT}, V_{OUT} \ge 1.0 \text{ V}$	-	0.2	0.4	V
Output High	R <sub>LOAD</sub> = 10 k to GND	-	V <sub>OUT</sub> – 0.2	V <sub>OUT</sub> – 0.4	V
Delay Time $R_{Delay} = 60 \text{ k}$		3.0 1.5	5.0 2.5	7.0 3.5	ms
Watchdog Input					
Threshold High	-	70	_	-	%V <sub>OUT</sub>
Threshold Low	-	-	-	30	%V <sub>OUT</sub>
Hysteresis	-	25	100	-	mV
Input Current	0 < WDI < 6.0 V	-10	0	+10	μА
Pulse Width	50% WDI falling edge to 50% WDI rising edge and 50% WDI rising edge to 50% WDI falling edge, (see Figure 5)		_	-	μs
Wake Up Output					
Wake Up Period	See Figures 4 and 5. R <sub>DELAY</sub> = 60 k	32 16	40 20	48 24	ms ms
Wake Up Duty Cycle Nominal	See Figure 3.	45	50	55	%
RESET HIGH to Wake Up Rising Delay Time	50% RESET rising edge to 50% Wake Up edge (see Figures 3 and 4) R <sub>DELAY</sub> = 60 k	16 8	20	24 12	ms ms
Wake Up Response to Watchdog Input	50% WDI falling edge to 50% Wake Up falling edge	_	2.0	10	μs
Wake Up Response to RESET	50% RESET falling edge to 50% Wake Up falling edge. V <sub>OUT</sub> = 5.0 V→ 4.5 V	-	2.0	10	μs
Output Low	R <sub>LOAD</sub> = 10 k	-	0.2	0.4	V
Output High	R <sub>LOAD</sub> = 10 k	_	V <sub>OUT</sub> – 0.2	V <sub>OUT</sub> – 0.4	

<sup>3.</sup> Measured when the output voltage has dropped 100 mV from the nominal value

**ELECTRICAL CHARACTERISTICS (continued)** ( $-40^{\circ}C \le T_{J} \le 125^{\circ}C$ ; 6.0 V  $\le$  V<sub>IN</sub>  $\le 28$  V, 100  $\mu$ A  $\le$  I<sub>OUT</sub>  $\le 150$  mA,  $C_{2}$  = 1.0  $\mu$ F, R<sub>Delay</sub> = 120 k; unless otherwise specified.)

Characteristic	Test Conditions	Min	Тур	Max	Unit
Delay					
Output Voltage	I <sub>DELAY</sub> = 50 μA. Note 4.	_	1.25	_	V

<sup>4.</sup> Current drain on the Delay pin directly affects the Delay Time, Wake Up Period, and the RESET to Wake Up Delay Time..

#### **PACKAGE PIN DESCRIPTION**

ı	PACKAGE PIN #			
TO-220 & D <sup>2</sup> PAK	SO-16L	SO-8	PIN SYMBOL	FUNCTION
1	8	4	V <sub>OUT</sub>	Regulated output voltage $\pm$ 2.0%.
2	9	5	V <sub>IN</sub>	Supply Voltage to the IC.
3	11	6	WDI	CMOS compatible input lead. The watchdog function monitors the falling edge of the incoming signal.
4	4, 5, 12, 13	2	GND	Ground connection.
5	14	7	WAKE UP	CMOS compatible output consisting of a continuously generated signal used to Wake Up the microprocessor from sleep mode.
6	15	8	RESET	CMOS compatible output lead RESET goes low whenever V <sub>OUT</sub> drops by more than 7.0% from nominal, or during the absence of a correct watchdog signal.
7	16	1	Delay	Buffered bandgap voltage used to create timing current for RESET and Wake Up from R <sub>Delay</sub> .
_	1, 2, 3, 6, 10	_	NC	No Connection.
-	7	3	Sense	Kelvin connection which allows remote sensing of the output voltage for improved regulation. Connect to V <sub>OUT</sub> if remote sensing is not required.

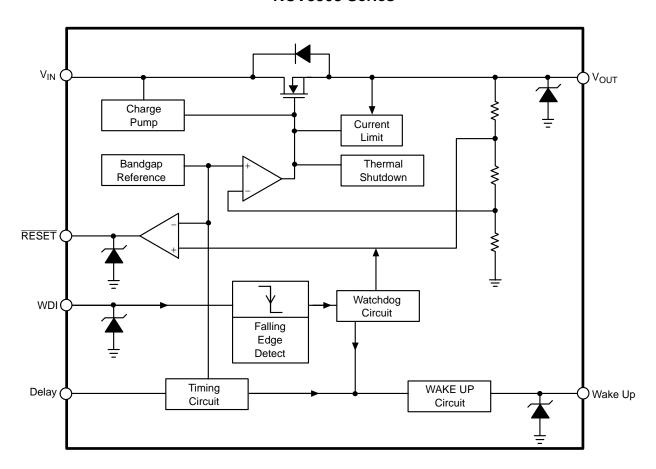


Figure 2. Block Diagram

#### **TIMING DIAGRAMS**

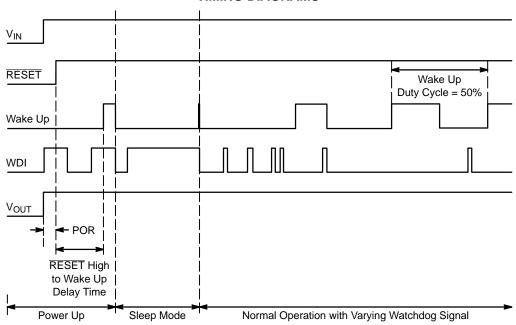


Figure 3. Power Up, Sleep Mode and Normal Operation

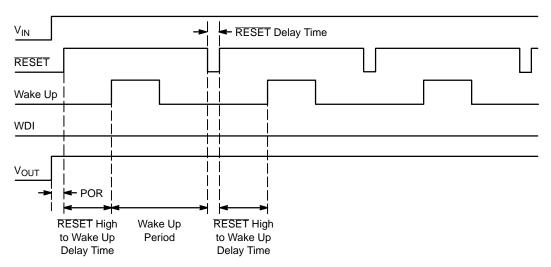


Figure 4. Error Condition: Watchdog Remains Low and a RESET Is Issued

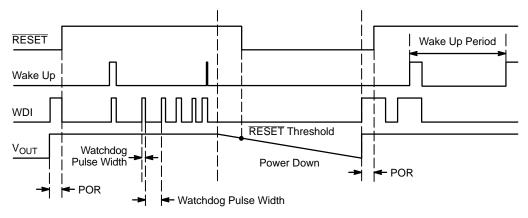


Figure 5. Power Down and Restart Sequence

#### **DEFINITION OF TERMS**

**Dropout Voltage:** The input–output voltage differential at which the circuit ceases to regulate against further reduction in input voltage. Measured when the output voltage has dropped 100 mV from the nominal value obtained at 14 V input, dropout voltage is dependent upon load current and junction temperature.

**Input Voltage:** The DC voltage applied to the input terminals with respect to ground.

**Line Regulation:** The change in output voltage for a change in the input voltage. The measurement is made under conditions of low dissipation or by using pulse techniques

such that the average chip temperature is not significantly affected.

**Load Regulation:** The change in output voltage for a change in load current at constant chip temperature.

**Quiescent Current:** The part of the positive input current that does not contribute to the positive load current. The regulator ground lead current.

**Ripple Rejection:** The ratio of the peak–to–peak input ripple voltage to the peak–to–peak output ripple voltage.

**Current Limit:** Peak current that can be delivered to the output.

#### DETAILED OPERATING DESCRIPTION

The NCV8508 is a precision micro–power voltage regulator with very low quiescent current (100 µA typical at 250 mA load). A typical dropout voltage is 250 mV at 150 mA. Microprocessor control logic includes Watchdog, Wake Up and RESET. This unique combination of extremely low quiescent current and full microprocessor control makes the NCV8508 ideal for use in battery operated, microprocessor controlled equipment in addition to being a good fit in the automotive environment.

The NCV8508 Wake Up function brings the microprocessor out of Sleep mode. The microprocessor in turn, signals its Wake Up status back to the NCV8508 by issuing a Watchdog signal.

The Watchdog logic function monitors an input signal (WDI) from the microprocessor. The NCV8508 responds to the falling edge of the Watchdog signal which it expects at least once during each wake-up period. When the correct Watchdog signal is received, a falling edge is issued on the wake-up signal line.

 $\overline{RESET}$  is independent of  $V_{IN}$  and operates correctly to an output voltage as low as 1.0 V. A signal is issued in any of three situations. During power up the  $\overline{RESET}$  is held low until the output voltage is in regulation. During operation if the output voltage shifts below the regulation limits, the  $\overline{RESET}$  toggles low and remains low until proper output voltage regulation is restored. And finally, a  $\overline{RESET}$  signal is issued if the regulator does not receive a Watchdog signal within the Wake Up period.

The  $\overline{RESET}$  pulse width, Wake Up signal frequency, and Wake Up delay time are all set by one external resistor,  $R_{Delay}$ .

The Delay pin is a buffered bandgap voltage (1.25 V). It can be used as a reference for an external tracking regulator like the CS8182.

The regulator is protected against short circuit and thermal runaway conditions. The device runs through 45 volt transients, making it suitable for use in automotive environments.

#### **CIRCUIT DESCRIPTION**

#### **Functional Description**

To reduce the drain on the battery a system can go into a low current consumption mode when ever its not performing a main routine. The Wake Up signal is generated continuously and is used to interrupt a microcontroller that is in sleep mode. The nominal output is a 5.0 volt square wave with a duty cycle of 50% at a frequency that is determined by a timing resistor,  $R_{Delay}$ .

When the microprocessor receives a rising edge from the Wake Up output, it must issue a watchdog pulse and check its inputs to decide if it should resume normal operations or remain in the sleep mode.

The first falling edge of the watchdog signal causes the Wake Up to go low within 2.0  $\mu$ s (typ) and remain low until the next Wake Up cycle (see Figure 6). Other watchdog pulses received within the same cycle are ignored (Figure 3).

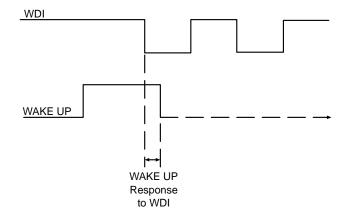


Figure 6. Wake Up Response to WDI

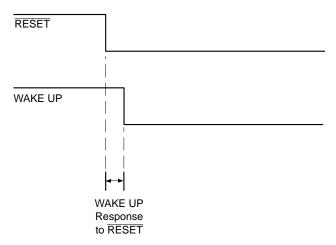


Figure 7. Wake Up Response to RESET (Low Voltage)

During power up,  $\overline{RESET}$  is held low until the output voltage is in regulation. During operation, if the output voltage shifts below the regulation limits, the  $\overline{RESET}$ 

toggles low and remains low until proper output voltage regulation is restored. After the RESET delay, RESET returns high.

The Watchdog circuitry continuously monitors the input watchdog signal (WDI) from the microprocessor. The absence of a falling edge on the Watchdog input during one Wake Up cycle will cause a RESET pulse to occur at the end of the Wake Up cycle. (see Figure 4).

The Wake Up output is pulled low during a RESET regardless of the cause of the RESET. After the RESET returns high, the Wake Up cycle begins again (see Figure 4).

The RESET Delay Time, Wake Up signal frequency and RESET high to Wake Up delay time are all set by one external resistor R<sub>Delay</sub>.

Wake Up period =  $(3.33 \times 10^{-7})$ R<sub>Delay</sub>

 $\overline{\text{RESET}}$  Delay Time =  $(4.17 \times 10^{-8}) R_{\text{Delay}}$ 

RESET HIGH to Wake Up Delay Time =  $(1.67 \times 10^{-7})$ R<sub>Delay</sub>

Capacitor temperature coefficient and tolerance as well as the tolerance of the NCV8508 must be taken into account in order to get the correct system tolerance for each parameter.

#### **APPLICATION NOTES**

# Calculating Power Dissipation in a Single Output Linear Regulator

The maximum power dissipation for a single output regulator (Figure 8) is:

$$PD(max) = {VIN(max) - VOUT(min)} + VIN(max)IQ$$
 (1) where:

V<sub>IN(max)</sub> is the maximum input voltage,

V<sub>OUT(min)</sub> is the minimum output voltage,

 $I_{OUT(max)}$  is the maximum output current for the application, and

 $I_Q$  is the quiescent current the regulator consumes at  $I_{OUT(max)}. \label{eq:lower}$ 

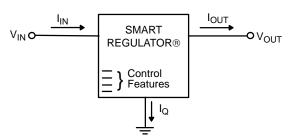


Figure 8. Single Output Regulator with Key Performance Parameters Labeled

Once the value of  $P_{D(max)}$  is known, the maximum permissible value of  $R_{\Theta JA}$  can be calculated:

$$R_{\Theta JA} = \frac{150^{\circ}C - T_{A}}{P_{D}}$$
 (2)

The value of  $R_{\Theta JA}$  can then be compared with those in the package section of the data sheet. Those packages with  $R_{\Theta JA}$ 's less than the calculated value in equation 2 will keep the die temperature below 150°C.

In some cases, none of the packages will be sufficient to dissipate the heat generated by the IC, and an external heatsink will be required.

#### **Heat Sinks**

A heat sink effectively increases the surface area of the package to improve the flow of heat away from the IC and into the surrounding air.

Each material in the heat flow path between the IC and the outside environment will have a thermal resistance. Like series electrical resistances, these resistances are summed to determine the value of  $R_{\Theta JA}$ :

$$R_{\Theta JA} = R_{\Theta JC} + R_{\Theta CS} + R_{\Theta SA}$$
 (3)

where:

 $R_{\Theta IC}$  = the junction-to-case thermal resistance,

 $R_{\Theta CS}$  = the case–to–heatsink thermal resistance, and

 $R_{\Theta SA}$  = the heatsink-to-ambient thermal resistance.

 $R_{\Theta JC}$  appears in the package section of the data sheet. Like  $R_{\Theta JA}$ , it too is a function of package type.  $R_{\Theta CS}$  and  $R_{\Theta SA}$  are functions of the package type, heatsink and the interface between them. These values appear in heat sink data sheets of heat sink manufacturers.

#### **ORDERING INFORMATION**

Device	Output Voltage	Package	Shipping
NCV8508T33		TO-220 STRAIGHT, 7-PIN	50 Units/Rail
NCV8508TV33		TO-220 VERTICAL, 7-PIN	50 Units/Rail
NCV8508D2T33		D <sup>2</sup> PAK, 7–PIN	50 Units/Rail
NCV8508D2T33R4	0.01/	D <sup>2</sup> PAK, 7–PIN	750 Tape & Reel
NCV8508D33	- 3.3 V	SO-8	95 Units/Rail
NCV8508D33R2		SO-8	2500 Tape & Reel
NCV8508DW33		SO-16L	46 Units/Rail
NCV8508DW33R2		SO-16L	1000 Tape & Reel
NCV8508T50		TO-220 STRAIGHT, 7-PIN	50 Units/Rail
NCV8508TV50		TO-220 VERTICAL, 7-PIN	50 Units/Rail
NCV8508D2T50		D <sup>2</sup> PAK, 7–PIN	50 Units/Rail
NCV8508D2T50R4	507	D <sup>2</sup> PAK, 7–PIN	750 Tape & Reel
NCV8508D50	5.0 V	SO-8	95 Units/Rail
NCV8508D50R2		SO-8	2500 Tape & Reel
NCV8508DW50	]	SO-16L	46 Units/Rail
NCV8508DW50R2		SO-16L	1000 Tape & Reel

#### **MARKING DIAGRAMS**

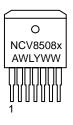




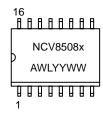




D<sup>2</sup>PAK 7-PIN **D2T SUFFIX** CASE 936H



SO-16L **DW SUFFIX CASE 751G** 



SO-8 **D SUFFIX CASE 751** 



= Voltage Ratings as Indicated Below: Х

3 = 3.3 V5 = 5.0 V

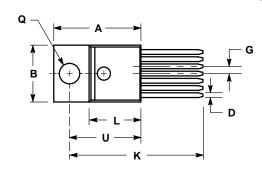
= Assembly Location

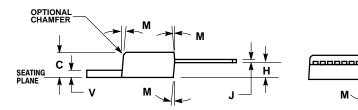
WL, L = Wafer Lot YY, Y = Year WW, W = Work Week

#### **PACKAGE DIMENSIONS**

TO-220 **SEVEN LEAD T SUFFIX** CASE 821E-04

ISSUE C





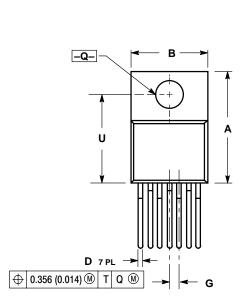
#### NOTES:

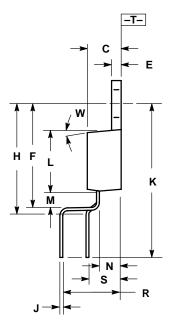
- TIES:

  1. DIMENSIONING AND TOLERANCING PER ANSI
  Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION D DOES NOT INCLUDE DAMBAR
- PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.003 (0.076) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.600	0.610	15.24	15.49
В	0.386	0.403	9.80	10.23
С	0.170	0.180	4.32	4.56
D	0.028	0.037	0.71	0.94
G	0.045	0.055	1.15	1.39
Н	0.088	0.102	2.24	2.59
J	0.018	0.026	0.46	0.66
K	1.028	1.042	26.11	26.47
L	0.355	0.365	9.02	9.27
M	5 ° NOM		5 ° N	IOM
Q	0.142	0.148	3.61	3.75
U	0.490	0.501	12.45	12.72
٧	0.045	0.055	1.15	1.39

#### TO-220 **SEVEN LEAD TV SUFFIX** CASE 821J-02 ISSUE A



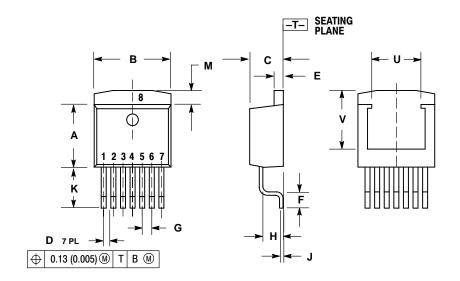


#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
- 1. DIMENSIONING AND TOLERANCING PER ANS Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION D DOES NOT INCLUDE INTERCONNECT BAR (DAMBAR) PROTRUSION. DIMENSION D INCLUDING PROTRUSION SHALL NOT EXCEED 10.92 (0.043) M

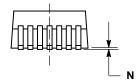
	INCHES		MILLIM	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.560	0.590	14.22	14.99
В	0.385	0.415	9.77	10.54
С	0.160	0.190	4.06	4.82
D	0.023	0.037	0.58	0.94
Е	0.045	0.055	1.14	1.40
F	0.540	0.555	13.72	14.10
G	0.050 BSC		1.27	BSC
Н	0.570	0.595	14.48	15.11
J	0.014	0.022	0.36	0.56
K	0.785	0.800	19.94	20.32
L	0.322	0.337	8.18	8.56
M	0.073	0.088	1.85	2.24
N	0.090	0.115	2.28	2.91
Q	0.146	0.156	3.70	3.95
R	0.289	0.304	7.34	7.72
S	0.164	0.179	4.17	4.55
U	0.460	0.475	11.68	12.07
W	3°		3	0

D<sup>2</sup>PAK 7-PIN **D2T SUFFIX** CASE 936H-01 **ISSUE O** 

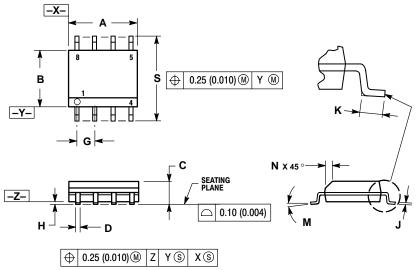


- NOTES:
  1. DIMENSIONS AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. TAB CONTOUR OPTIONAL WITHIN DIMENSIONS B AND M.
  4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH OR GATE PROTRUSIONS. MOLD FLASH AND GATE PROTRUSIONS NOT TO EXCEED 0.025 (0.635) MAX.

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.326	0.336	8.28	8.53
В	0.396	0.406	10.05	10.31
С	0.170	0.180	4.31	4.57
D	0.026	0.036	0.66	0.91
Е	0.045	0.055	1.14	1.40
F	0.058	0.078	1.41	1.98
G	0.05	0 BSC	1.27 BSC	
Н	0.100	0.110	2.54	2.79
J	0.018	0.025	0.46	0.64
K	0.204	0.214	5.18	5.44
M	0.055	0.066	1.40	1.68
N	0.000	0.004	0.00	0.10
U	0.25	0.256 REF		REF
٧	0.30	5 REF	7.75	REF



#### SO-8 **D SUFFIX** CASE 751-07 ISSUE W



#### NOTES:

- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
  4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
- 4. MAXIMUM MOLD PHOLHUSION 0.15 (0.006) PER SIDE.
  5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	4.80	5.00	0.189	0.197
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27	7 BSC	0.050 BSC	
Н	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
М	0 °	8 °	0 °	8 °
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

SO-16L DW SUFFIX CASE 751G-03

# 

#### NOTES:

- DIMENSIONS ARE IN MILLIMETERS.
- 2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
- DIMENSIONS D AND E DO NOT INLCUDE MOLD PROTRUSION.
- MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
   DIMENSION B DOES NOT INCLUDE DAMBAR
- DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF THE B DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS				
DIM	MIN	MAX			
Α	2.35	2.65			
A1	0.10	0.25			
В	0.35	0.49			
С	0.23	0.32			
D	10.15	10.45			
E	7.40	7.60			
е	1.27	BSC			
Н	10.05	10.55			
h	0.25	0.75			
L	0.50	0.90			
A	0 °	7°			

#### **PACKAGE THERMAL DATA**

Paramet	er	TO-220 7 LEAD	D <sup>2</sup> PAK 7–Pin	SO-8	SO-16L	Unit
$R_{\Theta JC}$	Typical	1.8	1.8	45	18	°C/W
$R_{\Theta JA}$	Typical	50	10–50*	165	75	°C/W

<sup>\*</sup>Depending on thermal properties of substrate.  $R_{\Theta JA} = R_{\Theta JC} + R_{\Theta CA}$ .

SMART REGULATOR is a registered trademark of Semiconductor Components Industries, LLC.

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer.

#### PUBLICATION ORDERING INFORMATION

#### Literature Fulfillment:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA

**Phone**: 303–675–2175 or 800–344–3860 Toll Free USA/Canada **Fax**: 303–675–2176 or 800–344–3867 Toll Free USA/Canada

Email: ONlit@hibbertco.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

**JAPAN**: ON Semiconductor, Japan Customer Focus Center 4–32–1 Nishi–Gotanda, Shinagawa–ku, Tokyo, Japan 141–0031

Phone: 81–3–5740–2700 Email: r14525@onsemi.com

ON Semiconductor Website: http://onsemi.com

For additional information, please contact your local Sales Representative.